



Mechanical Aspects in Electronics Systems Design

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GRIN Verlag Gmbh Aug 2014, 2014. Taschenbuch. Book Condition: Neu. 211x148x7 mm. This item is printed on demand - Print on Demand Neuware - Scientific Study from the year 2013 in the subject Engineering - Mechanical Engineering, grade: B+, , course: Electronics Systems Design, language: English, abstract: In chapter 1, the present research carried on the mature laser technology i.e. GaAs, in order to improve its efficiency. The packaging principle used for receivers can be applied for the packaging of the laser driver circuit and the laser source in a single module. The concept of FRACAS (Failure Reporting, Analysis and Corrective Action System) has been described and failure analysis technique for Electrical overstress (EOS) is described. An industrial approach to calculating the reliability of a system with some known data is described. Some challenges with respect to packaging has been discussed in detail and some methods to overcome challenges such as lattice mismatch has been described. Every electronic components or electronic systems have certain specifications based on which it is developed and all components have datasheets of their own. The datasheets consists complete details related to the product such as product design specifications, packaging type, power ratings, dimensions etc. Any...



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